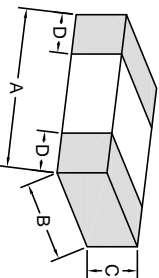


P/N: FASBL2012A102H

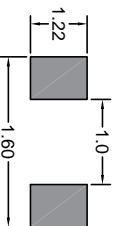


Outline Dimensions(Unit:mm)



A	B	C	D
±0.30	±0.20	±0.20	±0.3
2.0	1.25	0.85	0.5

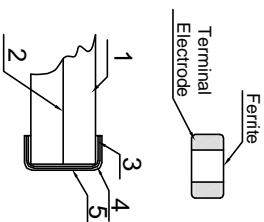
Recommended land pattern



Electrical Characteristics (@25°C)

Impedance (Ω)	Z Test Freq. (MHz)	DC Resistor	I _r (mA) Max
1000±25%	100	0.35 Ω Max	500

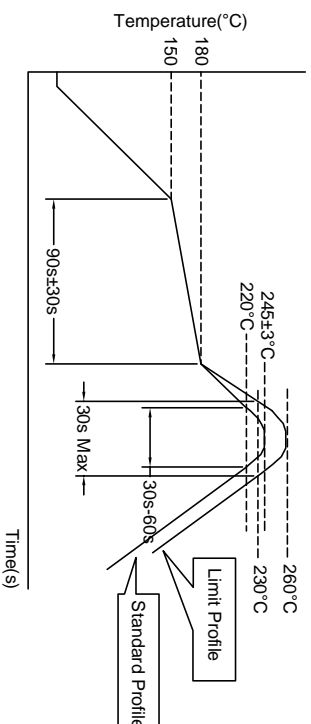
**Operating Temperature: -55°C~+125°C
 (**Temperature rise included)
 ***Storage Temperature: -55°C~+125°C
 ***Storage Humidity: RH20%~70%



List of UL Certificate:

NO	PART	MATERIAL
1	Ferrite substance	Ferrite
2	Silver electroded	Ag
3	Silver electroded	Ag
4	Ni plating	Ni
5	Sn plating	Sn

Recommended Soldering Temperature Graph.



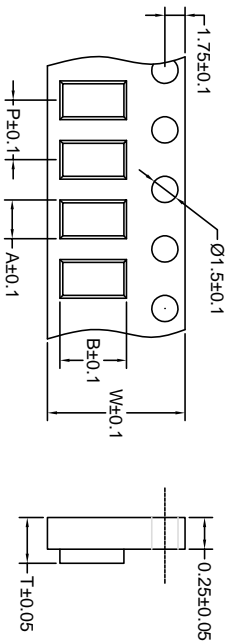
	Standard Profile	Standard Profile
Pre-heating	150~180°C, 90s±30s	
Heating	above 220°C, 30s-60s	above 240°C, 30s Max
Peak temperature	245°C±3°C	260°C, 10s
Cycle of reflow	2 times	2 times

REV01	DESCRIPTION	APPD	DATE	REV	DESCRIPTION	APPD	DATE	Tolerances unless otherwise specified: (X)±0.50 (XX)±0.25 Unit of measurement: mm		Drawn: Frank,Huang Checked: Anson Approved: Louis	DRAWING TITLE		Customer P/N: MMZ20125102A1T000 Document/Rev: 2301006/01 Specification Sheet: 1 of 2 Date of Recognition: Jan./05/2023
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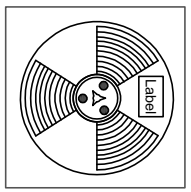
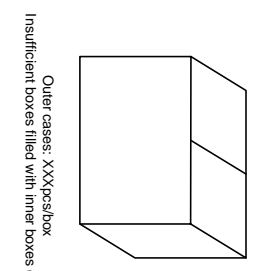
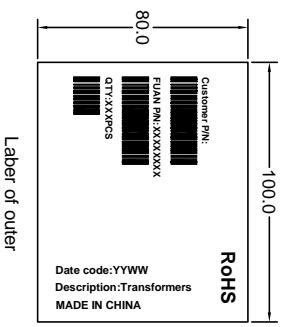
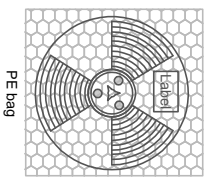
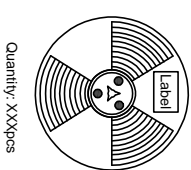
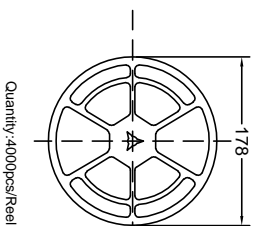
P/N: FASBL2012A102H



Packing Specifications (Unit:mm):



W	8.0
A	0.6
B	1.1
P	2.0
T	1.0



Description	QTY
Pieces per cell	1
Pieces per tray	TBD
Pieces per box	TBD
Net weight(g/pcs)	TBD
Net weight(g/box)	TBD
Gross weight(kg/box)	TBD

Boxes size dimensions (unit:mm):L*W*H (TBD)

Tianchang Fuan Electronic Co., Ltd
 www.fuantronics.net
 TEL: +86-0514-87693589
 E-mail: sales@fuantronics.net

Drawn: Frank,Huang
 Checked: Anson
 Approved: Louis

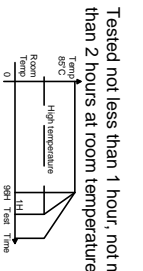
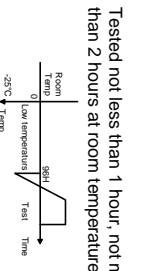
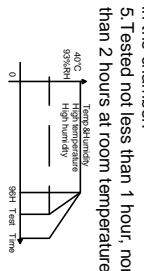
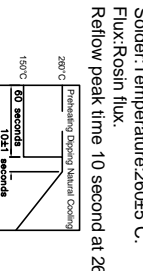
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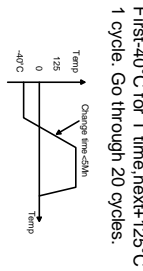
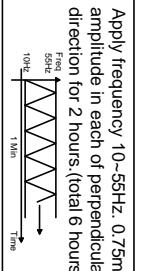
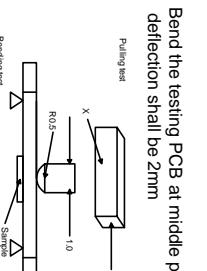
Customer P/N: MMZ20125102A1000
 Document/Rev: 2301006/01
 Specification Sheet: 2 of 2
 Date of Recognition: Jan/05/2023

Tolerances unless otherwise specified:
 (X)±0.50 (XX)±0.25
 Unit of measurement: mm



Reliability Testing:

Item	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%.	Temperature:85±2°C Time:96±2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Reference documents: IEC 68-2-1A 6.1.6.2	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%.	Temperature:25±2°C Time:96±2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%.	1.Dry oven at a temperature of 40±5°C for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature:40±2°C, Humidity: 93±3%RH Time:96±2 hours. 4. Tested while the specimens are still in the chamber. 5. Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%.	Preheat:150°C,60 second. Solder:Sn/Ag/Cu. Solder:Temperature:260±5°C. Flux:Rosin flux. Reflow peak time 10 second at 260°C 

Item	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%. For T ₁ :weight≤28g;1.5 Min 28g≤weight≤136g;30 Min	First-40°C for T time next+125°C T time as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at 245±5°C for 5 second. Solder:Sn(93.5)Ag(3.5). Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%.	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours. (total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2.ΔL/L≤10%. 3.ΔQ/Q≤30%. 4.ADCR/DCCR≤10%. For T ₁ :weight≤28g;1.5 Min 28g≤weight≤136g;30 Min	Packaged & Drop down from 1m with 981m/s2(100G)altitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321-1:1997	Pulling test: DEFINE:A:sectional area of terminal A≤8(Sq M) Force≥5N, time:30sec 8(Sq M)<A≤20(Sq M) Force≥10N, time:10sec 20(Sq M)<A force≥20N time:10sec Bending test: Soldering the products on PCB, after the pulling test and bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

Tianchang Fuan Electronic Co., Ltd
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Tolerances unless otherwise specified:
(X)H0.50 (XX)H0.25
Unit of measurement: mm

Drawn: Frank,Huang
Checked: Anson
Approved: Louis

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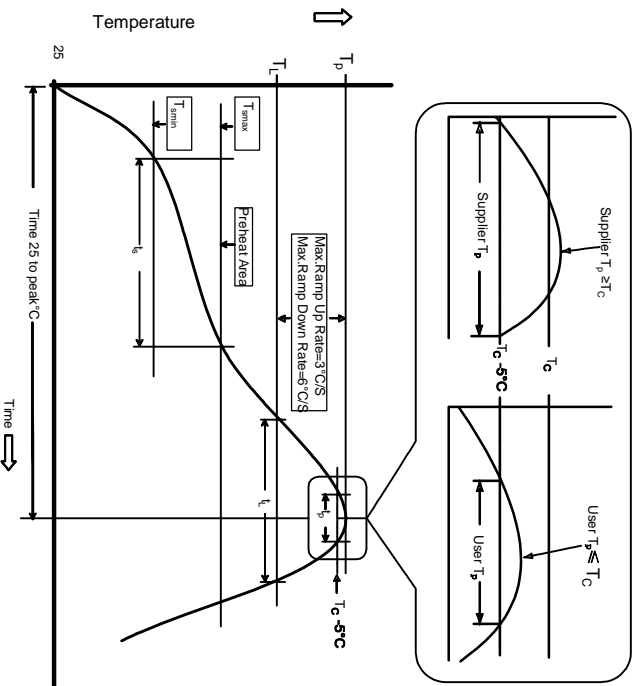
Customer P/N: MMZ20125102A1T000
Document/Rev: 23070006/01
Specification Sheet: 2 of 2
Date of Recognition: Jan/05/2023

P/N: FASBL2012A102H



Item	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar, smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



ITEM	Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
1	Temperature Min. (Tmin) Temperature Max. (Tmax) Time (ts) from (Tmin to Tmax)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-120 seconds
2	Preheat/Soak Ramp-up rate (TL to Tp)	3°C/second max.	3°C/second max.
3	Liquidus temperature (TL) Time (tl) maintained above TL	183 °C 60-150 seconds	217 °C 60-150 seconds
4	Peak package body temperature (Tp)	For users Tp must not exceed the Classification temp. in Table 4-1 (IPC/JEDEC J-STD-020D-1). For suppliers Tp must equal or exceed the Classification temp in Table 4-1 (IPC/JEDEC J-STD-020D-1).	For users Tp must not exceed the Classification temp. in Table 4-2 (IPC/JEDEC J-STD-020D-1). For suppliers Tp must equal or exceed the Classification temp in Table 4-2 (IPC/JEDEC J-STD-020D-1).
5	Time (tp)* within 5 °C of the specified classification temperature (Tc), see figure 5-1 (IPC/JEDEC J-STD-020D-1)	20* seconds	30* seconds
6	Ramp-down rate (Tp to TL)	6 °C/second max.	6 °C/second max.
7	Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Use rosin-based flux
Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
Use lead-free solder, use Sn-3.0Ag-0.5Cu solder
Standard thickness of solder paste: 0.12-0.15mm

Tianchang Fuan Electronic Co., Ltd
www.fuantronics.net
TEL: +86-0514-87693589
E-mail: sales@fuantronics.net

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Specification Sheet: 2 of 2
Date of Recognition: Jan/05/2023